

Part Number: **DDTxxxECA-(p)-F (Date Code 0833+)**
Weight (mg): 7.9998

p = package designator
See Data Sheet

p= 7, 13 x=123, 143, 114, 124, 144, 115

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon *	7440-21-3	100.00%	0.84	0.0672	1000000	8400
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	30.28	2.422	576500	174540
		Ni	7440-02-0	41.00%			410000	124131
		Mn	7439-96-5	0.60%			6000	1817
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	303
		Co	7440-48-4	0.50%			5000	1514
		Si	7440-21-3	0.15%			1500	454
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.56	0.045	1000000	5625
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.20	0.016	1000000	2000
Encapsulation	CEL-1620HF-9	Silica	60676-86-0	77.00%	67.40	5.392	770000	518993
		Basic Duromer: Epoxy resin (Compound of a polymeric network)	-----	11.00%			110000	74142
		Basic Duromer:Phenolic resin (Compound of polymeric network)	-----	6.60%			66000	44485
		Misc. system	-----	5.00%			50000	33701
		Carbon black	1333-86-4	0.40%			4000	2696
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.72	0.0576	1000000	7200
				Total	100.00	7.9998		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Hexavalent chromium compounds	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Lead and lead compounds	Radioactive Substances
Mercury and mercury compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Organic tin compounds	Tributyl Tin Oxide (TBTO)